

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

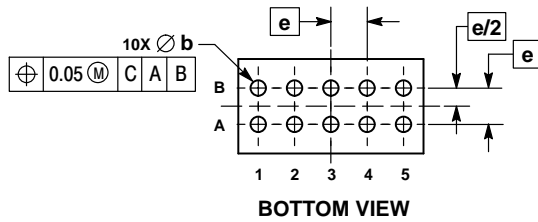
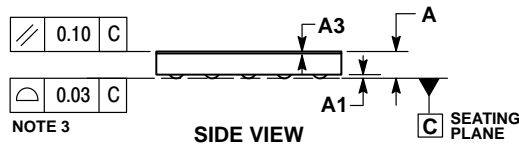
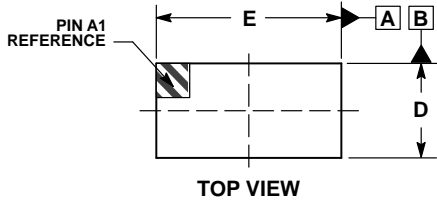
ON Semiconductor®



SCALE 4:1

WLCSP10, 1.04x2.04x0.265
CASE 567TH
ISSUE O

DATE 29 DEC 2016

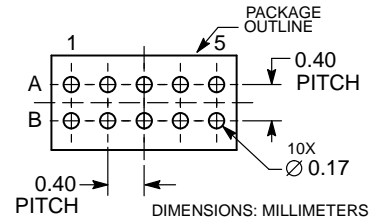


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.240	0.265	0.290
A1	0.040 REF		
A3	0.025 REF		
b	0.12	0.17	0.22
D	0.99	1.04	1.09
E	1.99	2.04	2.09
e	0.40 BSC		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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